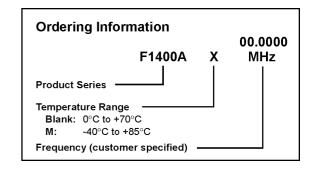
F1400A Series 9x14 mm FR-4, 5.0 Volt, Sinewave, Clock Oscillator

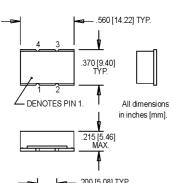


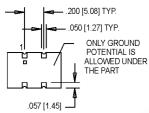


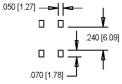
• Former Champion P

Product









SUGGESTED SOLDER PAD LAYOUT

Pin Connections

PIN	FUNCTION
1	N/C
2	Ground & Case Ground
3	Output
4	+Vdd

Frequency Range Frequency Stability ΔF/F	DADAMETED Symbol Mis To May Unite Condition										
Frequency Stability	PARAMETER		Symbol	Min.	Тур.	Max.	Units	Condition			
Overall	Frequ	Frequency Range		70		210	MHz				
Voltage, load, and aging 10°C to +70°C 240°C to +85°C 2435 24	Frequ	uency Stability	ΔF/F	0.							
Load		Overall					ature				
Load	-10	0°C to +70°C				±25	ppm				
Load	-40	0°C to +85°C				±35					
Load	မ်္ဗြ Oper	ating Temperature	TA	-40		+85	°C				
Load	Stora	age Temperature	Ts	-40		+85	°C				
Load	हु Input	Input Voltage		4.75	5.0	5.25	٧				
Load	मूं Input	t Current	ldd			40	mA				
Output Power	Outp	Output Signal		Sinewave							
Harmonics -20 dBc	Load					50	Ω				
Sub-Harmonics & Spurious Modes 10 ms 10 ms 10 kHz 10 kHz 100 kHz 155.520 Mhz -65 -95 -125 -145 -150 150 cycles; 10 min. dwell 155.520 Mhz MiL-STD-883, Method 2002, Condition B 1500 g's 1500 cycles; 10 min. dwell 1500 cycles; 10 cy	Outp	•		0	3	6	dBm				
Spurious Modes 10 ms 10 ms 10 MkL 10 MkL 10 MkL 100 MkL 100 MkL 155.520 Mhz -65 -95 -125 -145 -150 100 cycles; 10 min. dwell 100 cycles; 10 min. dwell 155.520 MkL 100 MkL 155.520 MkL 100 MkL 155.520 MkL 100 MkL 100 MkL 155.520 MkL 1	Harm					-20	dBc				
Phase Noise (Typical)						-70	dBc				
### ### ### ### ### ### ### ### ### ##	Start	up Time				10	ms				
Temperature Cycle	Phas	e Noise (Typical)	10 Hz	100 Hz	1 kHz	10 kHz	100 kHz	dBc/Hz			
Mechanical Shock MIL-STD-883, Method 2002, Condition B 1500 g's	@	155.520 Mhz	-65	-95	-125	-145	-150				
Vibration MIL-STD-883, Method 2007, Condition B 20-2000 Hz; 0.06 inch; 15 g's; 3 plan Humidity Steady State MIL-STD-202, Method 103 40°C; 90%-95% R.H.; 56 days Thermal Shock MIL-STD-883, Method 1011.7, Cond. B 100°C to 0°C; Water-to-Water; 15 cyc Electrostatic Discharge MIL-STD-883, Method 3015, Class II 2 KV to 4 KV Threshold Solderability MIL-STD-883, Method 2022.2 Solder dip; Meniscograph Criteria Hermeticity MIL-STD-883, Method 1014.8, Cond. A1 Mass spectro. 2 x 10-8 atoms. CC/sec Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Temp	Temperature Cycle MIL-STD-883, Method 1010, Condition B									
Humidity Steady State MIL-STD-202, Method 103 40°C; 90%-95% R.H.; 56 days Thermal Shock MIL-STD-883, Method 1011.7, Cond. B 100°C to 0°C; Water-to-Water; 15 cyc Electrostatic Discharge MIL-STD-883, Method 3015, Class II 2 KV to 4 KV Threshold Solderability MIL-STD-883, Method 2022.2 Solder dip; Meniscograph Criteria Hermeticity MIL-STD-883, Method 1014.8, Cond. A1 Mass spectro. 2 x 10-8 atoms. CC/se Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Mech	Mechanical Shock MIL		MIL-STD-883, Method 2002, Condition B			1500 g's				
Thermal Shock MIL-STD-883, Method 1011.7, Cond. B 100°C to 0°C; Water-to-Water; 15 cycle Electrostatic Discharge MIL-STD-883, Method 3015, Class II 2 KV to 4 KV Threshold Solderability MIL-STD-883, Method 2022.2 Solder dip; Meniscograph Criteria Hermeticity MIL-STD-883, Method 1014.8, Cond. A1 Mass spectro. 2 x 10-8 atoms. CC/set Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Vibra	ation	MIL-STD-883, Method 2007, Condition B				20-2000 Hz; 0.06 inch; 15 g's; 3 planes				
Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Humi	idity Steady State	MIL-STD-202, Method 103				40°C; 90%-95% R.H.; 56 days				
Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Therr	mal Shock	MIL-STD-883, Method 1011.7, Cond. B				100°C to 0°C; Water-to-Water; 15 cycles				
Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Ĕ Elect	trostatic Discharge	MIL-STD-883, Method 3015, Class II				2 KV to 4 KV Threshold				
Resistance to Soldering See "Figure 2" on page 147 Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	.º Sold€	Solderability MIL-STD-		883, Method 2022.2			Solder dip; Meniscograph Criteria				
Lead Integrity MIL-STD-883, Mtd. 2004.5, Cond. A,B1 Lead tension & bend stress	Herm	neticity	MIL-STD-	883, Method 1014.8, Cond. A1			Mass spectro. 2 x 10-8 atoms. CC/sec He				
	Resis	stance to Soldering	See "Figure 2" on page 147					_			
Marking Permanana MIL CTD 992 Method 2045 9	Lead	Lead Integrity MI		MIL-STD-883, Mtd. 2004.5, Cond. A,B1			Lead tension & bend stress				
Ivial King Permanence IviiL-5 D-883, Ivietnod 2015.8 Resistance to solvents	Mark	Marking Permanence		MIL-STD-883, Method 2015.8				Resistance to solvents			
Life Test MIL-STD-883, Method 1005.6 125°C, powered, 1000 hours minin	Life 1	Life Test		MIL-STD-883, Method 1005.6				125°C, powered, 1000 hours minimum			

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